Supplier Name:	Texas Instruments Inc. (DUNS# 00-732-1904)
Contact Info:	ti.com/support
Form/Declaration Type:	Distribute - RoHS and IEC 62474 DB
Created on:	08/26/2022

# Details for "OPA4131PA"

#### **Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
OPA4131PA	NIPDAU	Level-NC-NC-NC	TI AGUASCALIENTES	N   14	19.3x6.5x5.08	1611.2

#### \*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

# **Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

### **Component Information**

			Homogeneous Material Level		Component Level		
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.000002	0.000396	4	0	C
Precious Metals	Gold	7440-57-5	0.504526	99.996234	999962	0.031313	313
Precious Metals	Palladium	7440-05-3	0.000003	0.000595	6	0	C
Precious Metals	Silver	7440-22-4	0.000014	0.002775	28	0.000001	C
Sub-Total			0.504545	100	1000000	0.031315	313
Die Attach Adhesive							
Other Inorganic Materials	Silica	7631-86-9	0.043553	2.000008	20000	0.002703	
Precious Metals	Silver	7440-22-4	1.502572	68.999987	690000	0.093257	933
Thermoplastics	Epoxy	85954-11-6	0.631516	29.000005	290000	0.039195	392
Sub-Total			2.177641	100	1000000	0.135155	1352
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	391.15032	97.05	970500	24.27673	242767
Copper and Its Alloys	Iron	7439-89-6	10.47904	2.6	26000	0.650381	6504
Copper and Its Alloys	Phosphorus	7723-14-0	0.60456	0.15	1500	0.037522	375
Zinc and Its Alloys	Zinc	7440-66-6	0.80608	0.2	2000	0.050029	500
Sub-Total			403.04	100	1000000	25.014663	250147
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.722912	95.12	951200	0.044868	449
Precious Metals	Gold	7440-57-5	0.005928	0.78	7800	0.000368	4
Precious Metals	Palladium	7440-05-3	0.03116	4.1	41000	0.001934	19
Sub-Total			0.76	100	1000000	0.047169	472
Mold Compound	Mold Compound						
Other Inorganic Materials	Fused Silica	60676-86-0	1041.638278		870000	64.649242	646492
Other Organic Materials	Chlorine	7782-50-5	0.011973	0.001	10	0.000743	7
Other Organic Materials	Proprietary Non Halide Flame Retardant	Trade Secret	1.795928	0.15	1500	0.111464	1115
Thermoplastics	Epoxy	85954-11-6	153.839198	12.849	128490	9.548024	95480
Sub-Total			1197.285377	100	1000000	74.309474	743095
Semiconductor Device	Semiconductor Device						
Ceramics / Glass	Doped Silicon	7440-21-3	7.447428	100	1000000	0.462224	4622
Sub-Total			7.447428	100	1000000	0.462224	4622
Total			1611.214991			100	1000000

# Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component. The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.

See Glossary of Terms for more details.

## Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology For an explanation of the methods used to determine material weights, See Product Content Methodology

#### Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU ROHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

#### Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. Ti and Ti suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by Ti. The material content information is provided by Ti "as is." For additional information, please contact Ti customer support.

# Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 08/26/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet IS709B low halogen requirements of <= 1000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <= 1 000ppm threshold requirement: and Bervllium Oxide (BeO) is <=1000ppm.